

Abstract of the Disclosure

**SEMICONDUCTOR DEVICE HAVING A THERMOSET-CONTAINING
DIELECTRIC MATERIAL AND METHODS FOR FABRICATING THE SAME**

A semiconductor device having a thermoset-containing, dielectric material and methods for fabricating the same is provided. The device may take the form of a printed circuit board, an integrated circuit chip carrier, or the like. The dielectric material is a non-fibrillated, fluoropolymer matrix that has inorganic particles distributed therein and is impregnated with a thermoset material.

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